Lattice Semiconductor Corporation - LFECP15E-4F484I Datasheet



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	15400
Total RAM Bits	358400
Number of I/O	352
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfecp15e-4f484i

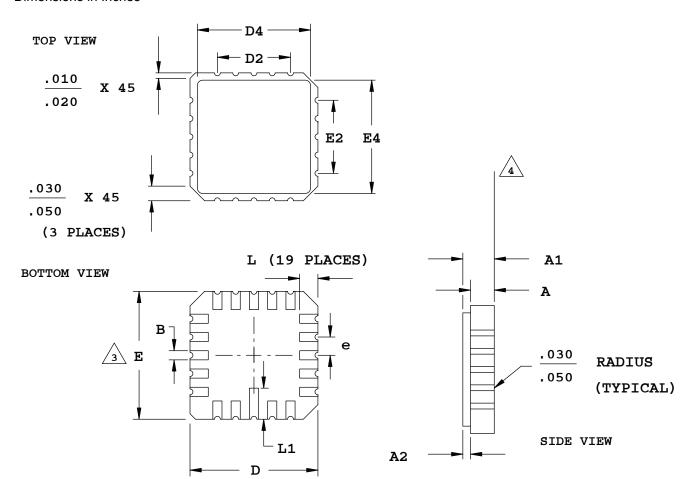
Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



20-Pin LCC Package

Dimensions in Inches



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5.
- ALL DIMENSIONS ARE IN INCHES.



3. DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .010 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .005 INCHES MAXIMUM PER SIDE.

3



FLATNESS TOLERANCE IS .004 INCHES PER INCH.

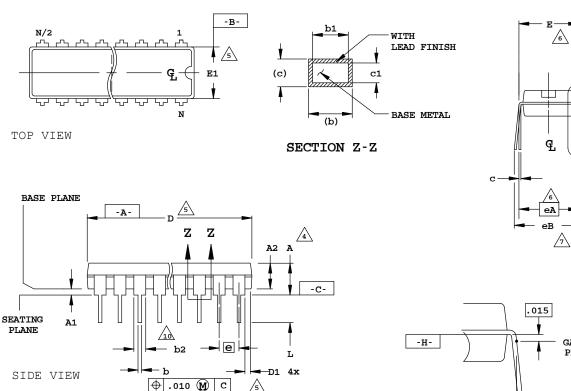
S Y M B	INCHES				
O L	MIN.		MAX.		
A	.054		.074		
A1	.064		.089		
A 2	.007		.015		
В	.022		.028		
D	.342		.358		
D2	.200				
D4	.270		.315		
E	.342		.358		
E2	.200				
E4	.270		.315		
е	.050 BSC				
L	.042		.058		
L1	.075		.095		

SEE DETAIL



20-Pin Plastic DIP Package

Dimensions in Inches



NOTES:

- 1. CONTROLLING DIMENSION: INCH.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
- 3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR
- PROTRUSIONS TO BE .005 MINIMUM. DIMENSIONS A, A1 & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING
- PLANE GAUGE GS-3.
- PLANE GAGE GS-3.

 DIMENSIONS D, D1 AND E1
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010

 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED

 TO BE PERPENDICULAR TO DATUM C-
- 70 BE PERPENDICULAR TO DATOM.

 eB AND eC ARE MEASURED AT THE LEAD TIPS

 with the Leads unconstrained. 8 N IS THE MAXIMUM NUMBER OF LEAD
- POSITIONS.

 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
- 10 b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
- 11 DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

-Н-	GAGE
	—— ec

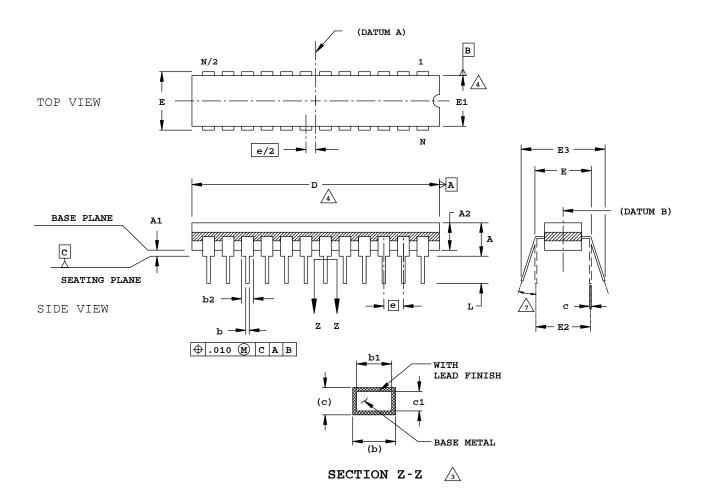
DETAIL A

]			
S Y M B	I	NCHES		N O T
O L	MIN.	T E		
Α	-	ı	.210	4
A 1	.015	-	-	4
A 2	.115	.130	.195	
b	.014	.018	.022	
b1	.014	.018	.020	
b2	.045	.060	.070	10
С	.008 .010		.014	
C1	.008	.010	.011	
D	.980	1.030	1.060	5
D1	.005	1	-	5
E	.300	.310	. 325	6
E1	.240	.250	.280	5
е				
eА		6		
eВ	-	-	.430	7
eC	.000	-	.060	7
L	.115	.130	.150	4



24-Pin (300-Mil) CERDIP

Dimensions in Inches



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.



MEASUREMENTS TO BE TAKEN AT A MINIMUM OF .060 INCHES FROM THE LEAD TIP.



DIMENSIONS D AND E1 INCLUDE ALLOWANCE FOR GLASS OVERRUN AND MENISCUS, AND LID TO BASE MISMATCH.

- 5. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-003.
- 6. E3 IS TO BE MEASURED AT THE LEAD TIPS.



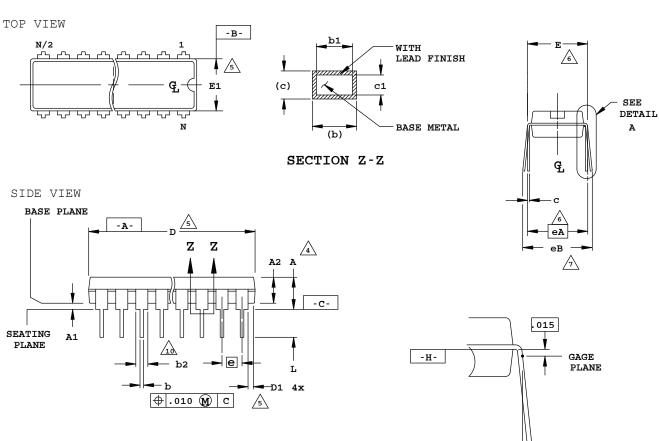
ALLOWED LEAD TIP POSITION RANGE.

S Y M B	INCHES				
o L	MIN.	NOM.	MAX.		
A	-	-	.200		
A1	.015	-	-		
A 2	.140	-	.175		
b	.015		.023		
b1	.015	.018	.021		
b2	.045	-	.065		
С	.008	-	.014		
c1	.008	.010	.012		
D	1.242	1.250	1.270		
E	.308		.325		
E1	.280	.288	.296		
E2	.300 REF				
E 3	.325	-	.410		
е	.1	00 BSC	;		
L	.125	-	.200		
N		24			



24-Pin Plastic DIP

Dimensions in Inches



NOTES:

- 1. CONTROLLING DIMENSION: INCH.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
- 3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR
- PROTRUSIONS TO BE .005 MINIMUM. 4 DIMENSIONS A, A1 & L ARE MEASURED WITH
- THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.

DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010

- 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED
- TO BE PERPENDICULAR TO DATUM -CeB AND eC ARE MEASURED AT THE LEAD TIPS
 with the LEADS UNCONSTRAINED.
- 8 N IS THE MAXIMUM NUMBER OF LEAD POSITIONS.
- 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
- 10 b2 MAXIMUM DIMENSIONS DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
- 11. DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

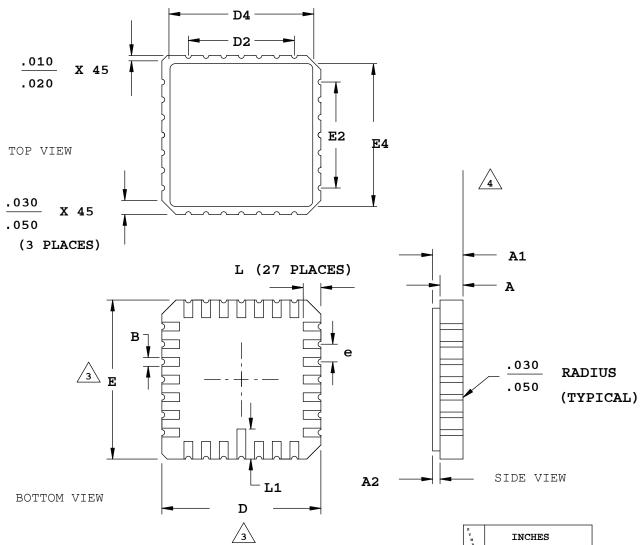
DETAIL A

	1			
s Y M	I	NCHES		
В 0				N T
L	MIN.	NOM.	MAX.	E
Α	-	-	.210	4
A1	.015	-	-	4
A 2	.115	.130	.195	
b	.014	.018	.022	
b1	.014	.018	.020	
b2	.045	.060	.070	10
С	.008 .010 .014			
c1	.008	.010	.011	
D	1.230	1.250	1.280	5
D1	.005	-	-	5
E	.300	.310	.325	6
E1	.240	.250	.280	5
е	.:			
eА		6		
еВ	-	-	.430	7
еC	.000	-	.060	7
L	.115	.130	.150	



28-Pin LCC Package

Dimensions in Inches



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5.
- 2. ALL DIMENSIONS ARE IN INCHES.

<u>/3.</u>

DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .010 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .005 INCHES MAXIMUM PER SIDE.



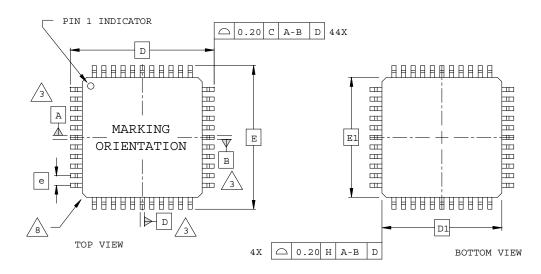
FLATNESS TOLERANCE IS .004 INCHES PER INCH.

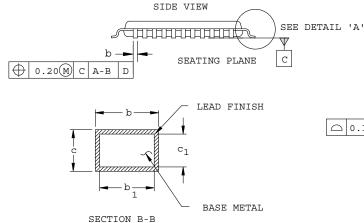
S Y M	INCHES				
0 L	MIN.		MAX.		
A	.054		.074		
A1	.064		.089		
A 2	.007		.015		
В	.022		.028		
D	.440		.460		
D2	.300				
D4	.370		.403		
E	.440		.460		
E2	.300				
E4	.370		.403		
е	. 0	50 BS	2		
L	.042		.058		
L1	.075		.095		

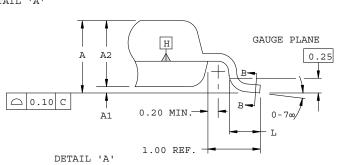


44-Pin TQFP Package (1.4 mm thick)

Dimensions in Millimeters







NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\stackrel{\textstyle >}{\scriptstyle 3}$ datums a, b and d to be determined at datum plane H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

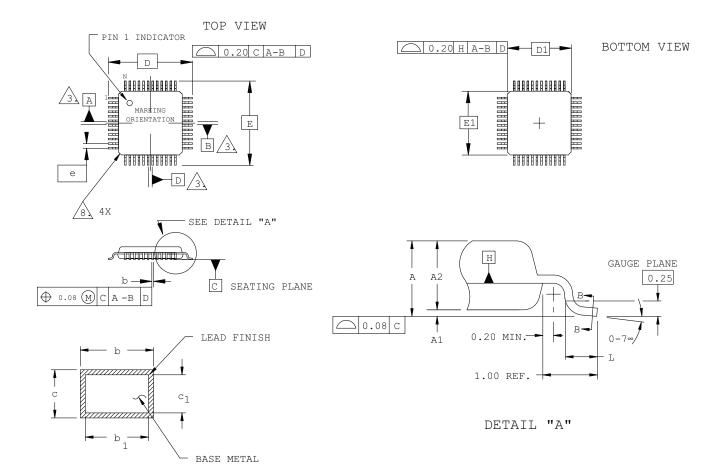
/8\ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.	
A	=	-	1.60	
A1	0.05	0.15		
A2	1.35	1.45		
D	12.00 BSC			
D1	10.00 BSC			
E	12.00 BSC			
E1	10.00 BSC			
L	0.45	0.75		
N	44			
е	0.80 BSC			
b	0.30	0.37	0.45	
b1	0.30	0.35	0.40	
С	0.09	0.15	0.20	
c1	0.09	0.13	0.16	



48-Pin TQFP Package (1.4 mm thick)

Dimensions in Millimeters



SECTION B - B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- $\sqrt{3}$ DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

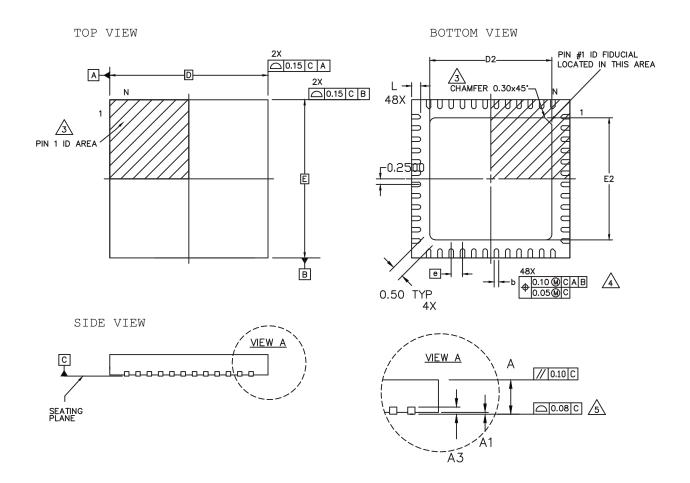
Λ							
/8\	EXACT	SHAPE	OF	EACH	CORNER	IS	OPTIONAL.
\sim							

SYMBOL	MIN.	NOM.	MAX.		
A	-	-	1.60		
A1	0.05	0.15			
A2	1.35	1.45			
D	9.00 BSC				
D1	7.00 BSC				
E	9.00 BSC				
E1	7.00 BSC				
L	0.45 0.60 0.75				
N	48				
е	0.50 BSC				
b	0.17	0.22	0.27		
b1	0.17	0.20	0.23		
С	0.09	0.15	0.20		
c1	0.09	0.13	0.16		



48-Pin QFN Package Option 2: L-ASC10, iCE40 Ultra, iCE40 UltraPlus, MachXO2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

<u> 3</u>

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

4

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

/5\

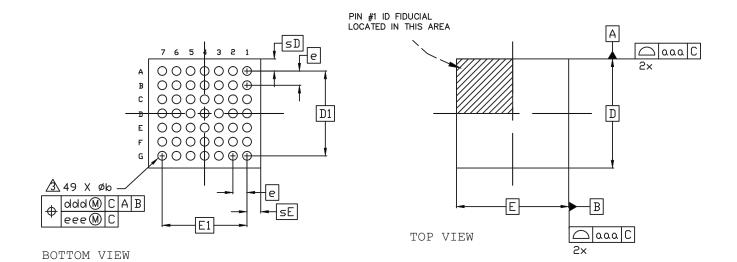
APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.	
А	0.80	0.90	1.00	
A1	0.00	0.02	0.05	
A3	0.2 REF			
D	7.0 BSC			
D2	5.30	5.40	5.50	
E	7.0 BSC			
E2	5.30	5.40	5.50	
b	0.15	0.20	0.25	
е		0.50 BSC		
L	0.35	0.40	0.45	



49-Ball WLCS Package

Dimensions in Millimeters



M bbb C A A

SIDE VIEW

Notes:

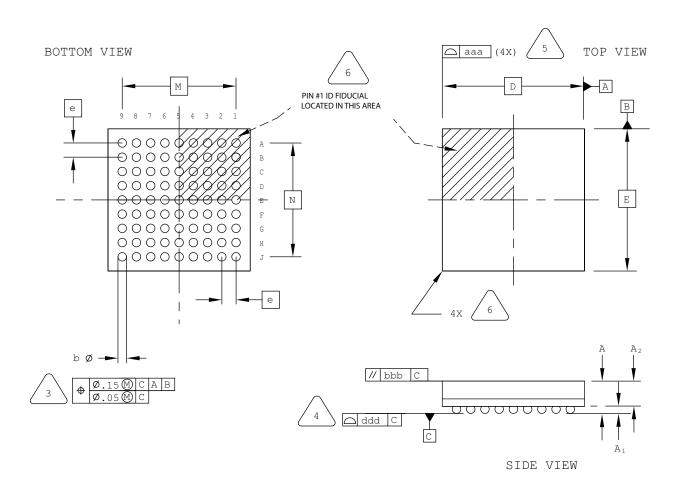
- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- riangle PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

REF.	Min.	Nom.	Max.
A	_		0.600
A1	0.167	0.199	0.232
b	0.239	0.266	0.319
D	3.055	3.106	3.155
E	3.125	3.185	3.225
D1	2	.40 BSC	2
E1	2.40 BSC		
е	0	.40 BSC	
sD	0.353	_	0.383
sE	0.388	-	0.418
aaa	(0.030	
bbb	0.060		
ccc	0.050		
ddd	0.015		
eee	(0.050	
	•		



81-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

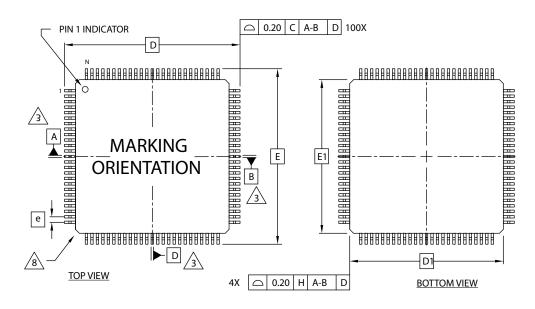


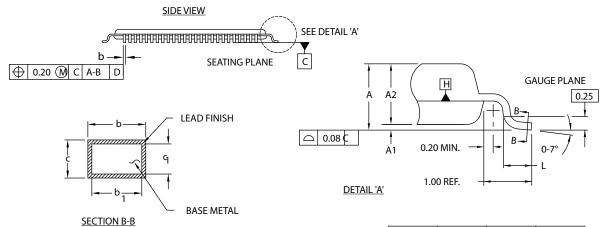
SYMBOL	MIN.	NOM.	MAX.	
А	-	-	1.00	
A1	0.10	_	_	
A2	-	_	0.90	
D/E	4.00 BSC			
M/N	3.20 BSC			
b	0.20	0.25	0.30	
е	0.40 BSC			
aaa	-	_	0.10	
bbb	_	_	0.10	
ddd	-	_	0.10	



100-Pin VQFP Package Option 2: iCE40

Dimensions in Millimeters





NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{3}$ DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

Λ.	
8.	EXACT SHAPE OF EACH CORNER IS OPTIONAL.

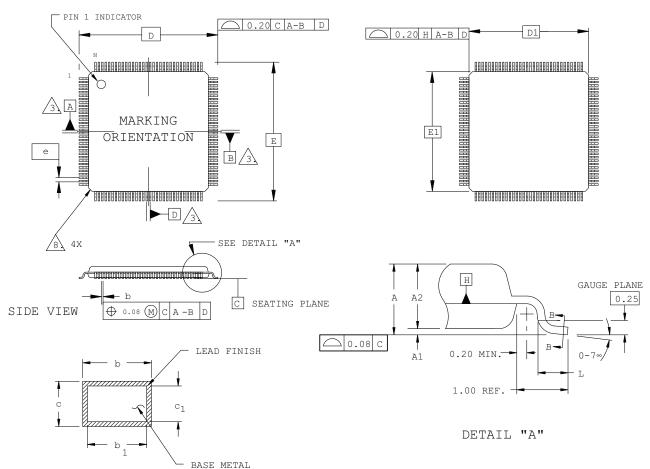
SYMBOL	MIN.	NOM.	MAX.
Α	1	-	1.20
A1	0.05	-	0.15
A2	0.95	1.00	1.05
D		16.00 BSC	
D1		14.00 BSC	
E	16.00 BSC		
E1	14.00 BSC		
L	0.45 0.60 0.75		
N	100		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
С	0.09	0.15	0.20
c1	0.09	0.13	0.16



176-Pin TQFP Package

Dimensions in Millimeters

TOP VIEW BOTTOM VIEW



SECTION B - B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{_3}$ DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

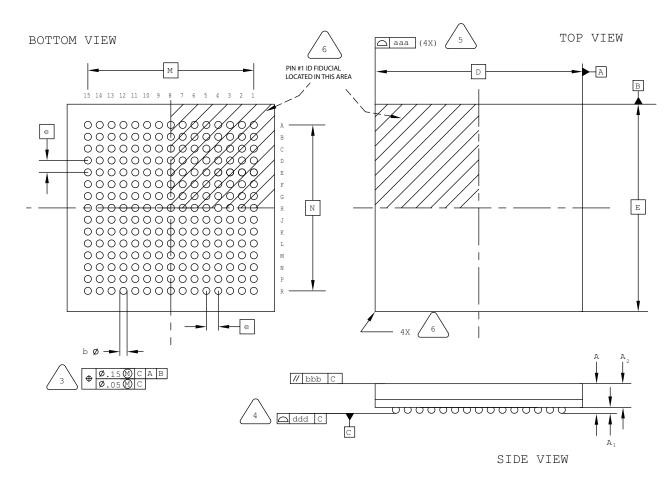
/\								
/8	7	EXACT	SHAPE	OF	EACH	CORNER	IS	OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.	
А	-	-	1.60	
A1	0.05	-	0.15	
A2	1.35	1.40	1.45	
D		26.00 BSC		
D1		24.00 BSC		
E	26.00 BSC			
E1	24.00 BSC			
L	0.45	0.60	0.75	
N	176			
е	0.50 BSC			
b	0.17	0.22	0.27	
b1	0.17	0.20	0.23	
С	0.09	0.15	0.20	
c1	0.09	0.13	0.16	



225-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

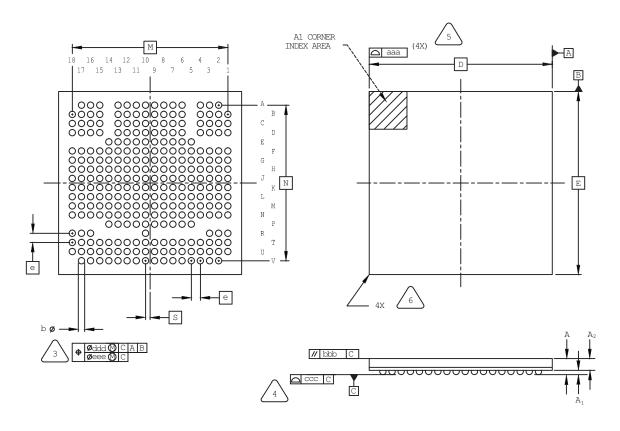


SYMBOL	MIN.	NOM.	MAX.	
А	ı	-	1.00	
A1	0.10	_	_	
A2	ı	-	0.90	
D/E	7.00 BSC			
M/N	5.60 BSC			
b	0.20	0.25	0.30	
е	0.40 BSC			
aaa	-	-	0.10	
bbb	-	_	0.10	
ddd	_	_	0.10	



285-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

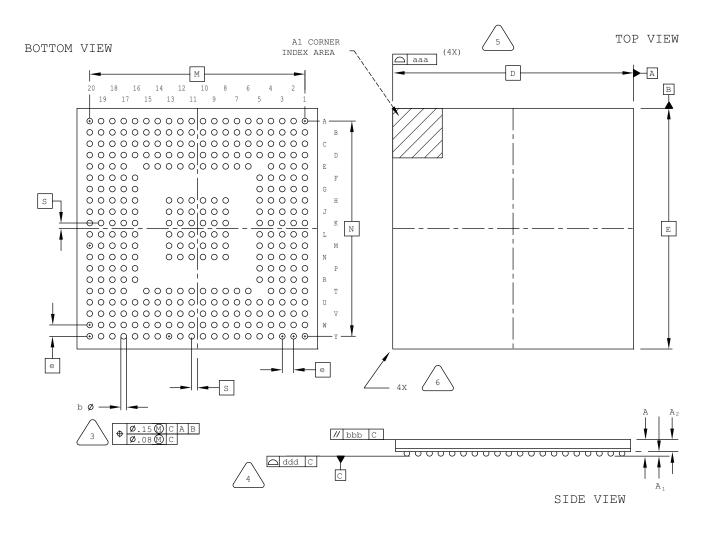


SYMBOL	MIN.	NOM.	MAX.	
А	-	-	1.30	
A1	0.15	_	_	
A2	-	-	1.00	
D/E	1	0.00 BSC		
M/N		8.50 BSC		
S		0.25 BSC		
b	0.25	0.35		
е	0.50 BSC			
aaa	0.10			
bbb	0.10			
ccc	0.08			
ddd	0.15			
eee		0.05		



332-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

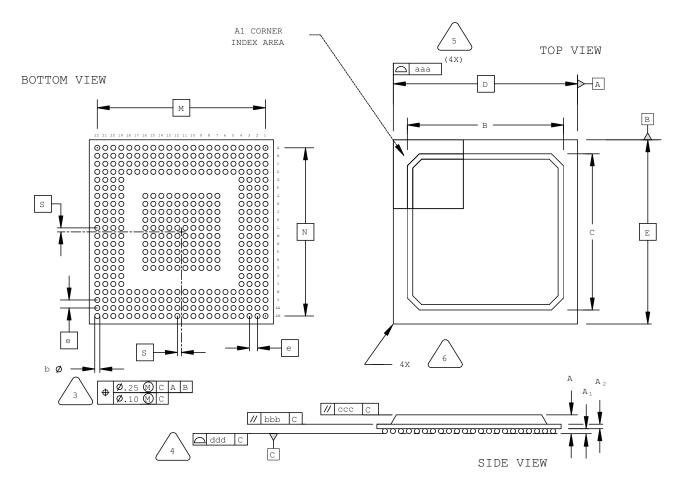


SYMBOL	MIN.	NOM.	MAX.	
А	-	-	2.00	
A1	0.25	_	_	
A2	0.65	_	_	
D/E	1	7.0 BSC		
M/N	15.2 BSC			
S	0.40 BSC			
b	0.40	0.45	0.50	
е	0.80 BSC			
aaa	-	-	0.15	
bbb	_	_	0.20	
ddd	_	_	0.20	



388-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

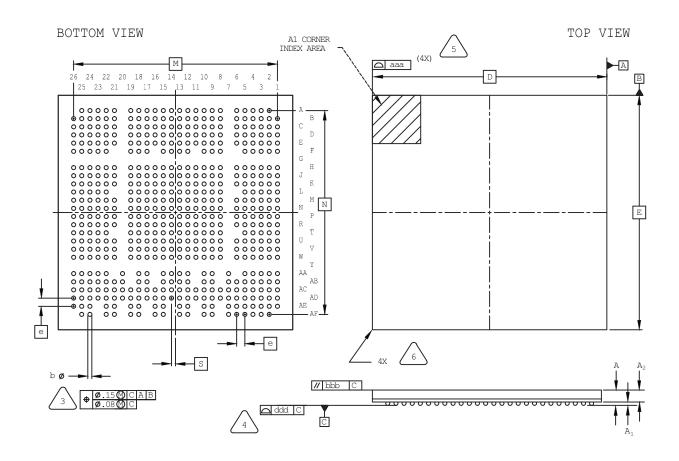


SYMBOL	MIN.	NOM.	MAX.
А	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	19.30	19.80	20.30
D/E	23	3.00 BSC	
M/N	21.00 BSC		
S		0.50 BSC	
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb			0.25
ccc	-	-	0.35
ddd	-	-	0.20



554-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{3}$

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{\mathbb{C}}$



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

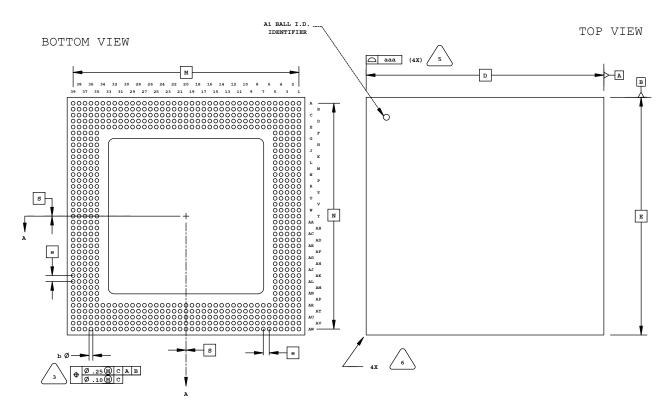


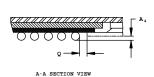
SYMBOL	MIN.	NOM.	MAX.		
А	-	-	1.76		
A1	0.25	0.30	0.35		
A2	0.80	_	_		
D/E	2.	23.0 BSC			
M/N	20.0 BSC				
S	0.40 BSC				
b	0.35	0.40	0.45		
е	0.80 BSC				
aaa	_	_	0.15		
bbb	_	_	0.20		
ddd	_	_	0.12		

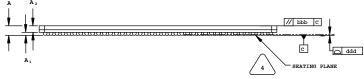


680-Ball fpSBGA Package

Dimensions in Millimeters







SIDE VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

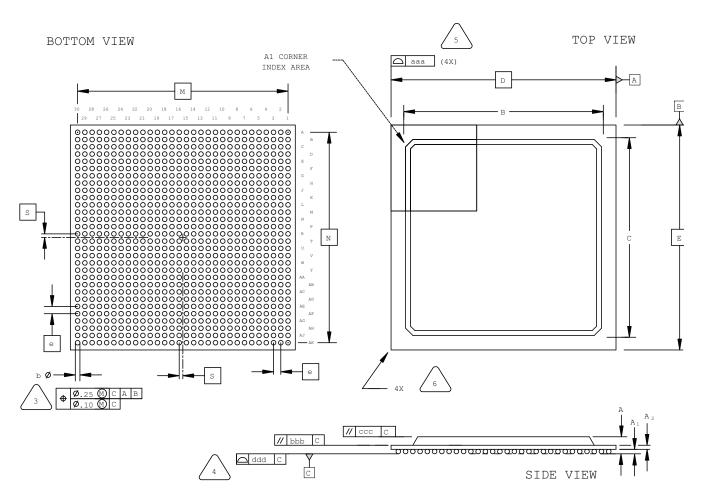


SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.45	0.53	0.60
A2	0.90	0.98	1.05
D/E	40	0.00 BSC	
M/N	31	3.00 BSC	
s	0.00 BSC		
b	0.50 0.65		0.80
е		1.00 BSC	
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20



900-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

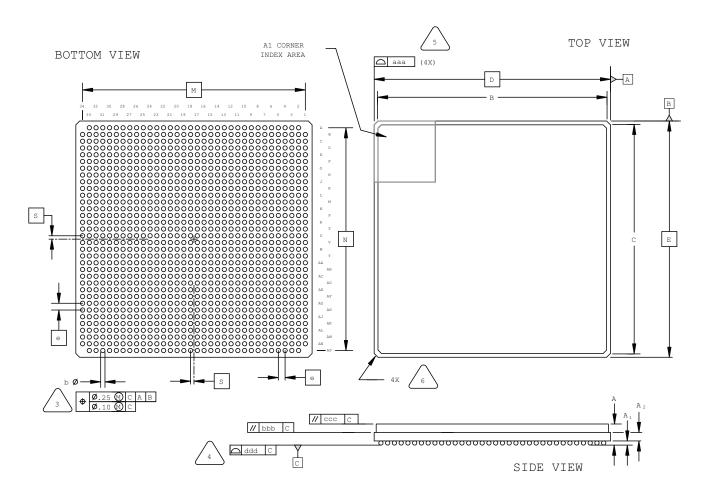


SYMBOL	MIN.	NOM.	MAX.
А	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	_	0.25
ccc	-		0.35
ddd	-	-	0.20



1152-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

 DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C





BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	4.00	4.60	5.20
A1	0.30	0.50	0.70
A2	1.40 REF		
B/C	33.10	34.00	34.90
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	_	-	0.20